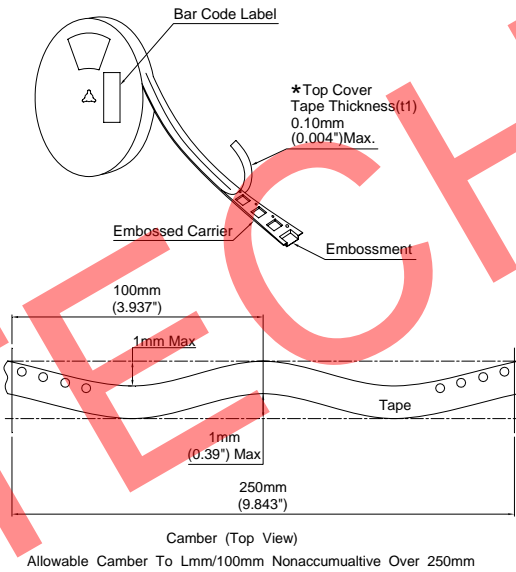
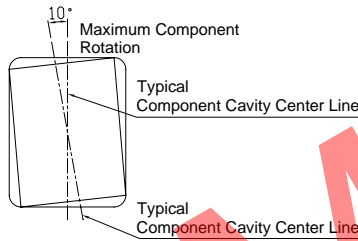
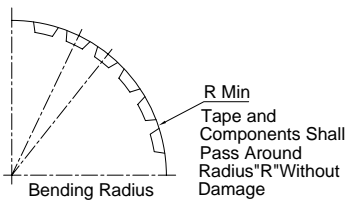
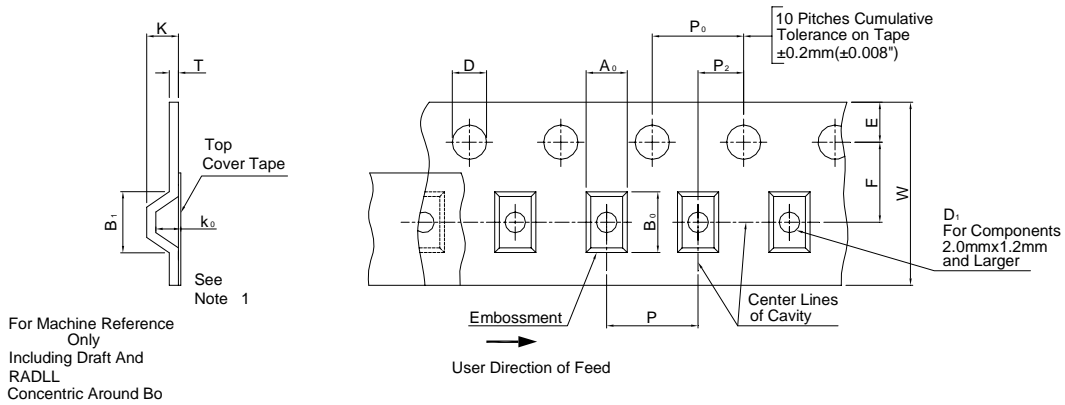


Embossed Tape and Reel Data for Surface Mounted Mold Diodes Carrier Tape Specifications



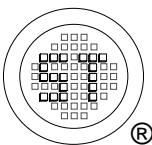
Dimensions

Tape Size	B1 Max.	D	D1	E	F	K	P0	P2	R Min.	T Max.	W Max.
8 mm	4.55mm (0.179")	1.5 +0.1mm -0.0	1.0 Min (0.039")	1.75 ± 0.1 mm (0.069 ± 0.004)	3.5 ± 0.05 mm (0.138 ± 0.002")	2.4 mm Max (0.094")	4 ± 0.1 mm (0.157 ± 0.004")	2 ± 0.1 mm (0.079 ± 0.002")	25 mm (0.98")	0.6 mm (0.024")	8.3 mm (0.327")
12 mm	8.2mm (0.323")	0.059 + 0.004"-0.0	1.5 mm Min (0.060")	-	5.5 ± 0.05 mm (0.217 ± 0.002")	6.4 mm Max (0.252")	-	-	30 mm (1.18")	-	12 ± 0.30 mm (0.47 ± 0.012")
16 mm	12.1mm (0.476")	-	-	-	7.5 ± 0.10 mm (0.295 ± 0.004")	7.9 mm Max (0.311")	-	-	-	-	16.3 mm (0.642")
24 mm	20.1mm (0.791")	-	-	-	11.5 ± 0.10 mm (0.453 ± 0.004")	11.9 mm Max (0.468")	-	-	-	-	24.3 mm (0.957")

Metric dimensions govern-English are in parentheses for reference only.

Note 1: A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min. to 0.5 mm max. The component cannot rotate more than 10° within the determined cavity.

Note 2: If B₁ exceeds 4.2 mm(0.165") for 8 mm embossed tape, the tape may not feed through all tape feeders.



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Dated : 24/02/2009